

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-5 (Canceled):

Claim 6 (Previously Presented): A semiconductor device comprising:

a die pad;
a die pad supporter which supports the die pad;
a plurality of inner leads arranged to surround the die pad; and
a semiconductor chip which has a size larger in area than that of said die pad
and which is mounted on said die pad;

wherein said die pad supporter includes a frame portion which has a rectangular shape, a first portion connected between a side portion of said frame portion and the die pad, and a second portion which extends from a corner portion of said frame portion to between a pair of said inner leads, and wherein the frame portion and the first portion are disposed between the inner leads and the die pad.

Claim 7 (Previously Presented): A semiconductor device according to claim 6, comprising a plurality of said second portions, wherein each of said second portions is

disposed between said inner leads and disposed substantially parallel with said inner leads adjacent to the second portions.

Claim 9 (Previously Presented): A semiconductor device according to claim 6, wherein said semiconductor chip has a first surface on which an integrated circuit is formed and a second surface which is opposite said first surface, and wherein said frame portion is arranged adjacent the second surface of the semiconductor chip.

Claim 10 (Previously Presented): A semiconductor device comprising:

- a die pad;
- a plurality of inner leads arranged to surround the die pad;
- a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;
- a frame portion which substantially surrounds the die pad and is disposed between said inner leads and said die pad;
- first die pad supporters each of which supports the frame portion from four directions; and
- a second die pad supporter which connects the frame portion and said die pad; wherein said second die pad supporter is extended along a direction different from directions in which the first die pad supporters are extended.

Claim 11 (Previously Presented): A semiconductor device according to claim 10, wherein said semiconductor chip is disposed on the frame portion.

Claim 12 (Previously Presented): A semiconductor device according to claim 11, wherein said first die pad supporters and said second die pad supporter are staggered at the frame portion.

Claim 13 (Previously Presented): A semiconductor device according to claim 10, wherein said frame portion has substantially rectangular shape, and wherein said first die pad supporters each support substantially corner portions of said frame portion, and wherein said second die pad supporter connects at a side portion of said frame portion.

Claims 14-15 (Canceled)

Claim 16 (Previously Presented): A semiconductor device according to claim 6, wherein said second portion of said die pad supporter has a down-set portion which is located at an area between the pair of said inner leads.

Claim 17 (Previously Presented): A semiconductor device according to claim 10, wherein said first die pad supporters have a down-set portion which is located at an

area between respective pairs of said inner leads.

Claims 18-22 (Canceled)